CORNING

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CORNING ADVANCED OPTICS

Corning to Unveil Microwave Industry's First-Ever Plated Polymer Connector at IMS 2024

CORNING, N.Y. | Corning Incorporated | May 29, 2024

New Corning® Gilbert® POLYLINK™ connector technology will help minimize costs and maximize installation flexibility for the telecommunications and aerospace industries.

Corning Incorporated (NYSE: GLW) announced today that it will launch its Corning® Gilbert ® POLYLINK™ technology at the 2024 International Microwave Symposium. POLYLINK is the radio-frequency and microwave-connectivity industry's first gold-plated plastic microwave connector. Reduced manufacturing lead times, compatible interfaces, and strong performance for up to 26.5 GHz make it an affordable, flexible option for telecommunications and aerospace customers.

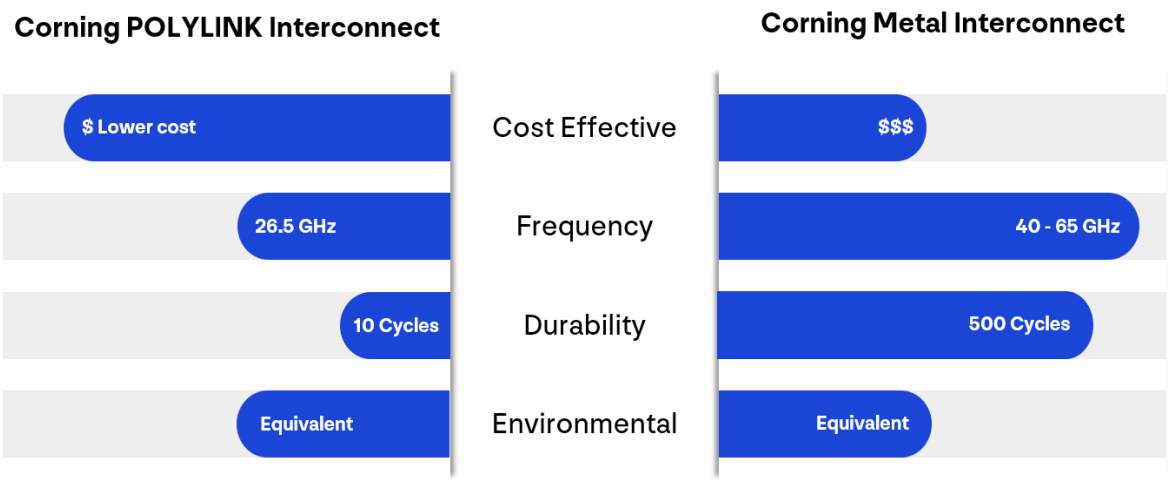
What: IEEE MTT-S International Microwave Symposium

When: June 18-20, 2024

Where: Booth 1213 – 2024 International Microwave Symposium, Walter E. Washington Convention Center, 801 Allen Y. Lew Place NW, Washington, D.C. 20001

Building on Corning Gilbert's six decades of pioneering microwave designs, the new technology is:

- **Lighter:** POLYLINK is up to 33% lighter than similar-sized Corning Gilbert beryllium copper-based interconnects, weighing only .06 grams with a center-to-center spacing of .0135 inches.
- **More Flexible:** The connector series allows up to .005 axial compression of the interconnect for applications in telecommunications, 5G, high-frequency commercial networks, aerospace and defense industries, and automotive radar/sensing.
- **Cost efficient:** POLYLINK is a gold-plated plastic blindmate interconnect that provides a cost advantage over beryllium-copper-plated blindmate interconnects.
- **Faster to make:** Robust supply chain availability and the quick molding speed for plastic polymer materials results in reduced manufacturing lead times as compared to our traditional interconnects.



“We’re proud to offer customers an excellent alternative for low-to-medium frequencies, especially when payload and cost efficiency matter most,” said Scott Flint, Business Director, Aerospace and Defense, Corning Advanced Optics. “This industry first demonstrates how Corning’s innovations are vital to the microwave connectivity field.”

East Coast Microwave will be the lead distributor of POLYLINK interconnects. Corning’s ongoing collaboration with East Coast reinforces the companies’ shared commitment to serving the radio frequency and microwave industry.

At the symposium, Corning experts will also showcase Corning Gilbert’s traditional metal blindmate interconnects. These connectors are trusted by customers for use in telecommunications, radar systems, shipboard, airborne, and ground-based missile programs, and for cryogenic and non-magnetic applications.

For more information about Corning’s future-defining microwave solutions, visit corning.com/microwave.

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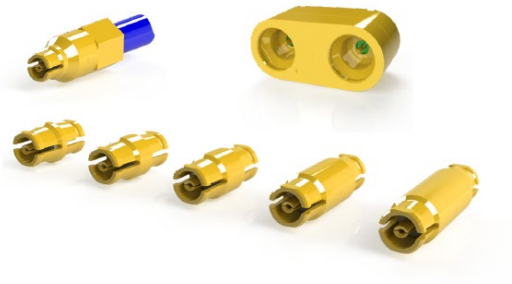
Multimedia



About Corning Incorporated

Corning (www.corning.com) is one of the world's leading innovators in materials science, with a 170-year track record of life-changing inventions. Corning applies its unparalleled expertise in glass science, ceramic science, and optical physics along with its deep manufacturing and engineering capabilities to develop category-defining products that transform industries and enhance people's lives. Corning succeeds through sustained investment in RD&E, a unique combination of material and process innovation, and deep, trust-based relationships with customers who are global leaders in their industries. Corning's capabilities are versatile and synergistic, which allows the company to evolve to meet changing market needs, while also helping our customers capture new opportunities in dynamic industries. Today, Corning's markets include optical communications, mobile consumer electronics, display, automotive, solar, semiconductors, and life sciences.